

IN THE CLAIMS:

Please amend the claims as follows.

1. (Currently Amended) An incombustible resin composition comprising a silicone oligomer which comprises an aromatic group, a metal hydrate which comprises aluminum hydroxide, and a resin material, wherein the metal hydrate is 20% by weight or more of in the total solids of the resin composition, and wherein the resin material is a resin other than said silicone oligomer.

2. (Currently Amended) The incombustible resin composition according to claim 1, wherein a resin material is selected from ~~the group consisting of~~ an epoxy resin, a polyimide resin, a triazine resin, a phenol resin, melamine resin and denatured resins denaturing these resins.

3. (Original) The incombustible resin composition according to claim 1, wherein the metal hydrate has a surface processed with a silicone oligomer.

4. (Canceled)

5. (Canceled)

6. (Original) The incombustible resin composition according to claim 1, wherein the metal hydrate includes magnesium hydroxide.

7. (Original) The incombustible resin composition according to claim 1, wherein the metal hydrate includes calcium hydroxide.

8. (Original) The incombustible resin composition according to claim 1, wherein an end of the silicone oligomer has a silanol group capable of reacting with ~~the~~ a surface of a metal hydrate.

9. (Currently Amended) The incombustible resin composition according to claim 1, wherein a degree of polymerization of the silicon oligomer is in the range of 2 to 7000.

10. (Canceled)

11. (Canceled)

12. (Currently Amended) A prepreg manufactured ~~by using~~ from the incombustible resin composition according to claim 1.

13. (Currently Amended) A laminated plate manufactured ~~by using~~ from the prepreg according to claim 12.

14. (Currently Amended) A metal-clad laminated plate manufactured ~~by using~~ from the prepreg according to claim 12.

15. (Currently Amended) A printed wiring board prepared ~~by using~~ from the laminated plate according to claim 13.

16. (Currently Amended) A multi-layer printed wiring board prepared ~~by using~~ from the prepreg according to claim 12.

17. (Currently Amended) A method for preparing an incombustible resin composition, which comprises: blending a metal hydrate which comprises aluminum

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hydroxide with a processing liquid containing silicone oligomer which comprises an aromatic group, and then blending other resin components, wherein the other resin components are resins other than said silicone oligomer.

18. (Canceled)

19. (Currently Amended) A printed wiring board prepared ~~by using~~ from the metal-clad laminated plate according to claim 14.

20. (Previously Presented) The incombustible resin composition according to claim 1, wherein each siloxane unit of the silicone oligomer has at least one aromatic group.

21. (Previously Presented) The incombustible resin composition according to claim 1, wherein the aluminum hydroxide has an average particle diameter of 5 μm or less.